Texas Instruments

Bill of Materials

TI DESIGNS

TIDA-00895

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint
1	1	!PCB1		Printed Circuit Board	Any	PWR532	
2	4	C1, C2, C3, C5	0.1uF	Capacitor, Ceramic, 50 V, X7R, 10%	Samsung Electromechanics	CL10B104KB8SFNC	0603
3	6	C4, C6, C7, C8, C10, C13	0.1uF	Capacitor, Ceramic Chip, 16V, X7R, 10%	Samsung Electromechanics	CL05B104KO5NNNC	0402
4	1	C9	1uF	Capacitor, Ceramic Chip, 16V, X5R, 10%	Samsung Electromechanics	CL05A105KO5NNNC	0402
5	1	C11	2.2uF	Capacitor, Ceramic Chip, 16V, X5R, 20%	TDK Corporation	C1005X5R1C225M050BC	0402
6	1	D1	BAS16-7-F	Diode, Ultrafast, 75V, 0.3A, SOT-23	Diodes Inc.	BAS16-7-F	SOT-23
7	2	D2, D3	MM3Z5V6C	Diode, Zener, 5.6V, 200mW	Fairchild	MM3Z5V6C	SOD323
8	6	FID1, FID2, FID3, FID4,		Fiducial mark. There is nothing to buy or mount.	N/A	N/A	Fiducial
9	2	J1, J2	ED555/3DS	Terminal Block, 3-pin, 6-A, 3.5mm	OST	ED555/3DS	0.41 x 0.25 inch
10	1	J3		Header (friction lock), 100mil, 4x1, R/A, TH	Molex	22-05-3041	4x1 R/A Header
11	1	LBL1		Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	Brady	THT-14-423-10	PCB Label 0.650"H x
12	3	P1, P2, P3	PEC02SAAN	Header, male 2-Pin, 100-mil spacing	Sullins	PEC02SAAN	0.100 x 2
13	1	Q1	SI1414DH-T1-GE3	MOSFET, Nch, 30V, 4A, 46 milliOhms	Vishay	SI1414DH-T1-GE3	SC-70
14	2	Q2, Q3	25V	MOSFET, N-CH, 25V, 52A, SON 5x6mm	Texas Instruments	CSD16412Q5A	SON 5x6mm
15	1	Q4	2N7002K-T1-E3	MOSFET, Nch, 60V, 300 mA, 2-Ohms	Vishay	2N7002K-T1-E3	SOT23
16	1	R1	1K	Resistor, Chip, 1/10-W, 5%	Samsung Electromechanics	RC1608J102CS	0603
17	8	R2, R15, R16, R18, R19, R20, R22, R23	100	Resistor, Chip, 1/16W, 5%	Samsung Electromechanics	RC1005J101CS	0402
18	3	R3, R4, R12	1k	Resistor, Chip, 1/16W, 5%	Samsung Electromechanics	RC1005J102CS	0402
19	2	R5, R6	10M	Resistor, Chip, 1/16W,5%	Samsung Electromechanics	RC1005J106CS	0402
20	1	R7	10K	Resistor, Chip, 1/10-W, 5%	Samsung Electromechanics	RC1608J103CS	0603
21	1	R8	100k	Resistor, Chip, 1/16W, 5%	Samsung Electromechanics	RC1005J104CS	0402
22	4	R9, R10, R13, R17	5.1k	Resistor, Chip, 1/16W, 5%	Samsung Electromechanics	RC1005J512CS	0402
23	1	R11	10	Resistor, Chip, 1/16W, 5%	Samsung Electromechanics	RC1005J100CS	0402
24	1	R14	4.99	Resistor, Chip, 1/16W, 5%	Vishay Dale	CRCW04024R99FKED	0402
25	1	R24	0.001 50ppm	Resistor, Metal Foil, 1 watt, ± 1%	Vishay	CSNL1206FT1L00	1206
26	1	RT1	10K	Thermistor, NTC, 3-A	Semitec	103AT-2	0.095 X 0.150 inch
27	1	S1	EVQ-PLHA15	Switch, Push button, Momentary, 1P1T, 50-mA, 12-V	Panasonic	EVQ-PLHA15	0.200 x 0.200 inch
28	10	TP1, TP3, TP4, TP5, TP7, TP8, TP10, TP12, TP13, TP14	Black	Test Point, TH, Miniature, Black	Keystone	5001	Keystone5001
29	3	TP2, TP6, TP9	Red	Test Point, TH, Miniature, Red	Keystone	5000	Keystone5000
30	1	U1	BQ294502DRVR	Overvoltage Protection Device for 2 to 3 Cell Li-Ion Batteries, with 4.35 V OVP, -40 to 85 degC, 6-pin SON (DRV), Green (RoHS & no Sb/Br)	Texas Instruments	BQ294502DRVR	DRV0006A
31	1	U2	bq28z610DRZ	1-Cell to 2-Series Cell Programmable Battery Manager, DRZ0012A	Texas Instruments	bq28z610DRZ	DRZ0012A
32	1	W1		Cable assembly, 4 pin Edge # 6575051	Any	SMBUS CBL002	N/A
33	0	C12	1uF	Capacitor, Ceramic Chip, 16V, X5R, 10%	Samsung Electromechanics	CL05A105KO5NNNC	0402

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34	0	C14, C15	0.1uF	Capacitor, Ceramic Chip, 16V, X7R, 10%	Samsung Electromechanics	CL05B104KO5NNNC	0402
35	0	J4		Header (friction lock), 100mil, 4x1, R/A, TH	Molex	22-05-3041	4x1 R/A Header
36	0	R21	330k	Resistor, Chip, 1/16W, 5%	Samsung Electromechanics	RC1005J334CS	0402
37	0	SPK1, SPK2, SPK3, SPK4, SPK5		Gap, 0.010" space			0.020 x 0.020 inch
38	0	TP11	Black	Test Point, TH, Miniature, Black	Keystone	5001	Keystone5001

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